Apex Microtechnology
Materials Substance Report

Model: PA75CD **Print: 07/17/2025**
RoHS Complaint: No **Lead Free: Yes**

Die Substances	Total Weight (g)
Aluminum	1.36E-05
Gold	7.77E-06
Nickel	8.97E-06
Silicon	3.57E-03
Silver	9.80E-04
Titanium	2.28E-06

Encapsulant Substances	Total Weight (g)
Carbon Black	1.30E-03
Metal Hydroxide	3.26E-02
Epoxy Resin 1	1.95E-02
Epoxy Resin 2	1.30E-02
Hardener	1.95E-02
Silica	5.67E-01

Lead Frame Substances	Total Weight (g)
Copper Alloy	5.04E-01
Iron	1.51E-04
Silica (fused)	1.92E-01
Epoxy resin	2.50E-02
Phenol resin	2.42E-02
Carbon black	7.81E-04
Metal hydroxide	7.50E-03

Solder substances	Total Weight (g)
Tin	2.84E-04
Lead	5.25E-03

Wire Substances	Total Weight (g)
Gold	8.37E-04

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Model: PA75CD **Print: 07/17/2025**
RoHS Complaint: No **Lead Free: Yes**

Substances Present in this Model	Total Weight (g)
Aluminum	1.36E-05
Carbon Black	2.08E-03
Copper Alloy	5.04E-01
Epoxy resin	2.50E-02
Epoxy Resin 1	1.95E-02
Epoxy Resin 2	1.30E-02
Gold	8.45E-04
Hardener	1.95E-02
Iron	1.51E-04
Lead	5.25E-03
Metal Hydroxide	4.01E-02
Nickel	8.97E-06
Phenol resin	2.42E-02
Silica	5.67E-01
Silica (fused)	1.92E-01
Silicon	3.57E-03
Silver	9.80E-04
Tin	2.84E-04
Titanium	2.28E-06
Grand Total	**1.42E+00**